

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"10/622,848"	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:19
L3	1	1 and align\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:22
L4	0	("2004/0056173").URPN.	USPAT	OR	ON	2005/04/17 15:21
L5	982	((250/559.19,559.27,559.22) or (356/630)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/17 15:22
L8	356	5 and height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:24
L9	59	8 and wafer and focus	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 16:55
L10	19	august.as. and inspect\$4 and height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:25
L11	91	map\$5 with wafer with height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:36
L12	62	11 and inspect\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 15:36
L13	0	("2005/0030528").URPN.	USPAT	OR	ON	2005/04/17 16:39
L14	0	"3d point sensor"	USPAT	OR	ON	2005/04/17 16:39
L15	1	"3d point sensor"	US-PGPUB; USPAT	OR	ON	2005/04/17 16:40
L16	11	"3d point" with (sensor detector)	US-PGPUB; USPAT	OR	ON	2005/04/17 16:40
L17	3	(wafer and focus\$4 and inspect\$5 and height).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 16:59
L18	5	("4972344" "5225886" "5929983" "6084664").PN. OR ("6597006").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 16:57
L19	0	((substrate sample die) and focus\$4 and inspect\$5 and height).ab.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 16:59

L20	11	(US-20040056173-\$ or US-20040239905-\$ or US-20040130691-\$ or US-20040080742-\$ or US-20040080737-\$ or US-20030230730-\$ or US-20030053676-\$).did. or (US-6324298-\$ or US-6876438-\$ or US-6597006-\$ or US-6215896-\$).did.	US-PGPUB; USPAT	OR	ON	2005/04/17 16:59
L21	11	20 and (camera CCD imag\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 17:01
L22	122	5 and (camera CCD imag\$4) and (wafer sample substrate die) and focus\$4 and height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 18:30
L23	0	("2003/0001117").URPN.	USPAT	OR	ON	2005/04/17 18:04
L24	1	("5629773").PN. OR ("6611344").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 18:29
L25	1415	(382/145,147,149,151).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/17 18:29
L26	2392	5 25	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 18:29
L27	240	26 and (wafer sample substrate die) and focus\$4 and height and inspect\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 18:30
L28	275	26 and focus\$4 and height and inspect\$5	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 18:30
L29	0	("2003/0053676").URPN.	USPAT	OR	ON	2005/04/17 18:36
L30	0	"10/242,362"	USPAT	OR	ON	2005/04/17 18:37
L31	1	"10/242,362"	US-PGPUB; USPAT	OR	ON	2005/04/17 18:37
L32	15	(US-20040056173-\$ or US-20040239905-\$ or US-20040130691-\$ or US-20040080742-\$ or US-20040080737-\$ or US-20030230730-\$ or US-20030053676-\$ or US-20040021877-\$ or US-20030001117-\$).did. or (US-6324298-\$ or US-6876438-\$ or US-6597006-\$ or US-6215896-\$ or US-6611344-\$ or US-6333510-\$).did.	US-PGPUB; USPAT	OR	ON	2005/04/17 19:29

L33	7	32 and interpolat\$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 19:58
L34	15	32 and height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:04
L35	13	32 and points	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:14
L36	8	32 and point with (sensor detector)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:19
L37	12	32 and (sensor detector)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:26
L38	5	32 and (gold solder)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:37
L39	12	32 and (height with difference)	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:32
L40	3	38 and 39	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 22:15
L41	2	32 and interconnect	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:38
L42	2	32 and interconnect and height	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 20:38
L43	9	32 and depth	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 22:17
L44	7	32 and objective	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 22:26
L45	3	32 and confocal	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/17 22:26